



## **Silicon Wafer NA TC Chapter**

SEMICON West Standards Meetings

Tuesday, July 11, 2017

1:00 pm - 5:00 pm

Marriott Marquis, San Francisco, CA

### **AGENDA**

#### **1.0 Welcome / Call to Order**

- 1.1 Introductions
- 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
- 1.3 Agenda Review

#### **2.0 Review of Schedule for the next meeting (NA Spring, April, 2018)**

#### **3.0 Review and Approval of Previous Meeting Minutes (NA Spring 2017)**

#### **4.0 Liaison Report**

- 4.1 European Committee
- 4.2 Japan Committee

#### **5.0 Staff Report**

#### **6.0 Regulations Change Report (if applicable)**

#### **7.0 Ballot Review**

- 7.1 Doc. 5915, Line Item Revision to SEMI M1-1016: Specification For Polished Single Crystal Silicon Wafers (To add Illustration of Flatness Metrics for Silicon Wafers)
- 7.2 Doc. 6019A, Line Item Revision of SEMI M1-1016, Specification for Polished Single Crystal Silicon Wafers
- 7.3 Doc. 6041, Line Item Revision of M21-1110 Guide For Assigning Addresses To Rectangular Elements In A Cartesian Array
- 7.4 Doc. 6042A, Line Item Revision to SEMI MF1763-0706 (Reapproved 1111) Test Methods for Measuring Contrast of a Linear Polarizer (Title correction for conformance)
- 7.5 Doc. 6096, Line Item Revision to SEMI M53-0216 Practice for Calibrating Scanning Surface Inspection Systems Using Certified Depositions of Monodisperse Reference Spheres on Unpatterned Semiconductor Wafer Surfaces (Addition of a related information 2)
- 7.6 Doc. 6169, Line Item Revision to MF1390-1014: Test Method For Measuring Bow And Warp On Silicon Wafer By Automated Noncontact Scanning



## **8.0 Task Force Reports**

- 8.1** Int'l Advanced Wafer Geometry Task Force /Noel Poduje (SMS), Jaydeep Sinha
- 8.2** Int'l Automated Advanced Surface Inspection Task Force/ Kurt Haller (KLA-Tencor)
- 8.3** Int'l SOI Wafers TF/Gerd Pfeiffer (GlobalFoundries)
- 8.4** Int'l Test Methods TF/Dinesh Gupta (STA)
- 8.5** Int'l Polished Wafers (Substrates) TF/John Valley
- 8.6** Int'l Terminology TF/TBD

## **9.0 Old Business**

### **10.0 New Business**

- 10.1 5 Year Review
- 10.2 TEM Grid (Troy Morrison/Thermo Fisher Scientific)

### **11.0 Action Item Review**

- 11.1 Open Action Items
- 11.2 New Action Items

### **12.0 Next Meeting and Adjournment**

- 12.1 The next meeting of the NA Silicon Wafer committee is at NA Spring Standards Meetings, Mon-Tues, April, 2018, Milpitas, CA.